

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : Jan. 20, 2014

Expected First Date Code of Changed Product :1351

Description of Change (From) :

The current WLCSP back-end process flow is performed at two Fairchild Semiconductors sites: bumping is done at South Portland wafer fab, USA, the test and tape and reel are performed at the Penang plant, Malaysia.

Description of Change (To) :

The WLCSP back-end process flow will be performed at two companies: Fairchild semiconductor and Amkor Technology. Bumping will be done at AMKOR T5 plant in Taiwan, R.O.C. or Fairchild, South Portland.

The test and tape and reel will be performed at AMKOR T3 plant in Taiwan, R.O.C. or Fairchild, Penang.

To further ensure critical supply chain continuity to our customers, Fairchild is expanding the use of an existing and fully qualified source for alternate wafer level chip scale device processing. This change is planned to take effect immediately upon customer approval.

Timely approval of this PCN will help to protect your supply chain against any unforeseen supply disruptions

Affected Product(s):

FPF1204BUCX	FPF1204UCX	FSA8108BUCX
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Qualification Plan	Device	Package	Process	No. of Lots
Q20120214	FSA9590UCX	UCBBU030	Maine FS35 5-40S	1
Q20120214	FSA9485UCX	UCBBU025	Maine FS35 5-40S	1

Test Description:	Condition:	Standard :	Duration:	Results:
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/154
Highly Accelerated Stress Test	110C, 85%RH, 5.4/3.9V	JESD22-A110	264 hrs	0/45
Highly Accelerated Stress Test	110C, 85%RH, 3.5V	JESD22-A110	264 hrs	0/45
Temperature Cycle	-40C, 125C	JESD22-A104	1000 Cycles	0/154